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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Hideto Ohnuma	09/11/2008
Takashi SHINGU	09/11/2008
Tetsuya Kakehata	09/11/2008
Kazutaka KURIKI	09/11/2008
Shunpei Yamazaki	09/18/2008

RECEIVING PARTY DATA

Name:	Semiconductor Energy Laboratory Co., Ltd.
Street Address:	398, Hase
City:	Atsugi-shi, Kanagawa-ken
State/Country:	JAPAN
Postal Code:	243-0036

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12244414

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NAME OF SUBMITTER: April K. Saunders-Fuller

PATENT

REEL: 021687 FRAME: 0443

Total Attachments: 2

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PATENT REEL: 021687 FRAME: 0444

ASSIGNMENT

For valuable consideration, We, <u>Hideto OHNUMA of Atsugi</u>, <u>Kanagawa</u>, <u>Japan</u>, <u>Takashi SHINGU of Atsugi</u>, <u>Kanagawa</u>, <u>Japan</u>, <u>Tetsuya KAKEHATA of Isehara</u>, <u>Kanagawa</u>, <u>Japan</u>, <u>Kazutaka KURIKI of Ebina</u>, <u>Kanagawa</u>, <u>Japan and Shunpei YAMAZAKI of Setagaya</u>, <u>Tokyo</u>, <u>Japan</u> hereby assign to <u>Semiconductor Energy Laboratory Co.</u>, <u>Ltd.</u>, a <u>Japanese</u> corporation having a place of business at:

398, Hase, Atsugi-shi, Kanagawa-ken, 243-0036 Japan

and its successors and assigns (collectively hereinafter called "the Assignee"), the entire right, title and interest throughout the world in the inventions and improvements which are subject of an application for United States Patent signed by us this day, entitled METHOD FOR MANUFACTURING SOI SUBSTRATE, filed October 2, 2008, and assigned U.S. Serial Number 12/244, 414, and we authorize and request the attorneys appointed in said application to hereafter complete this assignment by inserting above the filing date and serial number of said application when known; this assignment including said application, any and all United States and foreign patents, utility models, and design registrations granted for any of said inventions or improvements, and the right to claim priority based on the filing date of said application under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes; and we authorize the Assignee to apply in all countries in our name or in its own name for patents, utility models, design registrations and like rights of exclusion and for inventors' certificates for said inventions and improvements; and we agree for ourselves and our respective heirs, legal representatives and assigns, without further compensation to perform such lawful acts and to sign such further applications, assignments, Preliminary Statements and other lawful documents as the Assignee may reasonably request to effectuate fully this assignment.

Signature	Hider Uhruma	
Name:	Hideto OHNUMA	
Date:	09/11/2017	
Signature	Takashi Shingu	
Name:	Takashi SHINGU	
Date:	09/11/2008	

PATENT REEL: 021687 FRAME: 0445

Attorney Docket No. 12732-0561001 Client Reference No. US10963

Tetsuya Signature Name: Tetsuya KAKEHATA 09/11/2008 Date: Signature Kazutaka KURIKI Name: 09/11/200f Date: Signature Shunpei XAMAZAK Name: 09/18/7008 Date:

RECORDED: 10/15/2008

PATENT REEL: 021687 FRAME: 0446